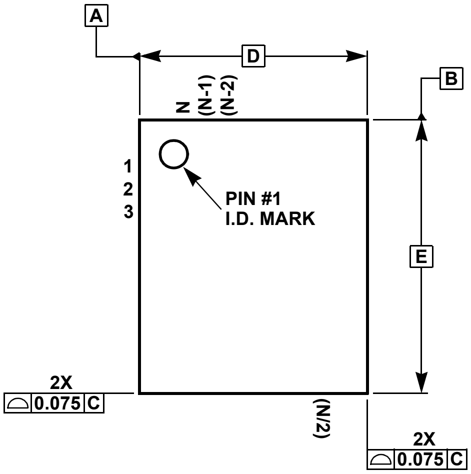
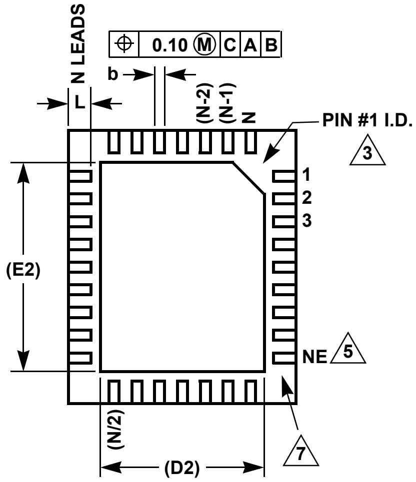
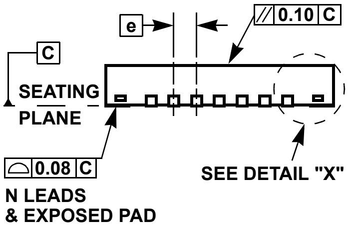
Thin Quad Flat No-Lead Plastic Package (TQFN)
Micro Lead Frame Plastic Package (MLFP)



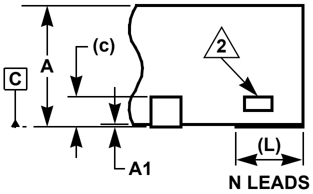
TOP VIEW



BOTTOM VIEW



SIDE VIEW



DETAIL X

L32.4x5A

32 LEAD THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE (COMPLIANT TO JEDEC MO-220)

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.70	0.75	0.80	-
A1	0.00	0.02	0.05	-
D	4.00 BSC			-
D2	2.50 REF			-
E	5.00 BSC			-
E2	3.50 REF			-
L	0.35	0.40	0.45	-
b	0.15	0.20	0.25	-
c	0.20 REF			-
e	0.40 BSC			-
N	32 REF			4
ND	7 REF			6
NE	9 REF			5

Rev 2 8/06

NOTES:

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Tiebar view shown is a non-functional feature.
3. Bottom-side pin #1 I.D. is a diepad chamfer as shown.
4. N is the total number of terminals on the device.
5. NE is the number of terminals on the “E” side of the package (or Y-direction).
6. ND is the number of terminals on the “D” side of the package (or X-direction). ND = (N/2)-NE.
7. Inward end of terminal may be square or circular in shape with radius (b/2) as shown.